

# Lin-Hung Lai (Henry)

Digital IC & Biochip Designer

## CONTACT

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## EDUCATION

Statistics ( Visiting PhD )  
Stanford University  
Wong Lab instituted by Wing Hong Wong  
2025 - 2026 (Expected)

Electronics Engineering ( PhD )  
National Yang Ming Chiao Tung University  
NYCU, Si2 Lab instituted by Chen-Yi Lee  
2021 - 2025 , GPA 4.3/4.3

Electronics and Computer Engineering ( BS )  
National Chiao Tung University  
2017 - 2021, Rank: 1/50

## SKILLS

### IC, Hardware Design & Verification

- Verilog, SystemVerilog
- Hspice, Virtuoso

### EDA Tools

- Design Compiler, VCS, Verdi
- Innovus, PrimeTime, Jaspergold

### Software Development

- C++, C, Python
- Shell Script, HTML

### System Integration

- FPGA, Vivado
- Raspberry Pi, Arduino
- PCB

## AWARDS

Bronze Medal Award, 2025  
**Macronix Golden Silicon Awards**

NYCU Student Affairs Office, 2024  
**Distinguished Contribution Award**

Scholastic Honor Society Awards, 2025  
**Phi Tau Phi Awards**

1st Prize Award, 2021  
**TSMC Intern Final Competition**

## EXPERIENCE

**Project Leader** Jan. 2021 - Apr. 2025

**System Integration & Silicon Implementation Lab, NYCU**

- Led 7 chip tape-outs, 6 IEEE papers, and 2 patents across TW/US/JP
- Built a CMOS capacitive sensor system to capture high-res cell images using multi-sampling and pixel-wise data fusion
- Managed 10+ graduate students, drove collaboration with CiRA Foundation and TVGH, and won the 2023 Taipei Biotech Award

**Sr. Teaching Assistant** 2021 Spr, 2021 Fal, 2023 Fal

**Integrated Circuit Design Lab, NYCU**

- Guided 300+ students across RTL to Layout projects; supervised 14 digital IC projects, including Low Power / CDC / STA / Verification etc
- Led 12 TAs in course delivery and debugging Verilog / SystemVerilog ASIC projects, awarded 2024 Prominent TA, 2023 Outstanding TA

**Hardware Engineer Intern** Jul. 2021 - Aug. 2021

**Division of System and Chip Design Solutions, TSMC**

- Built a 3DIC BGA optimizer (C++ / Python) for early-stage signal and power integrity planning in cell-based CAD flow
- Improved routing quality by 30%, won 1st place out of 100+ interns

**Lecturer of Logic Synthesis** 2024 Summer

**Taiwan Semiconductor Research Institute, TSRI**

## PROJECTS

### ProDEP: Silicon-Defined Digital Control of Living Cells

Capstone Research Project

- Enabled real-time single-cell manipulation using a full-custom CMOS chip (128×128 electrodes), integrated with FPGA, WiFi-RPi interface, Python GUI and optical feedback portable system
- Demonstrated full-stack silicon-to-system ownership, leading to startup spin-off (CyensTech, NT\$7.2M funding)

### CDC-Proven FIFO on 16nm FinFET – From RTL to APR

Integrated Circuit Design Laboratory Project

- Built an async FIFO using gray code and handshake synchronizers, solving multi-clock domain issues with formal check (JasperGold).
- Implemented on TSMC 16nm ADFP, integrating clock gating, 2-port SRAM, and full RTL→APR flow with power/timing analysis
- Gained hands-on experience solving metastability, process scaling

### 16-bit RISC CPU with AXI and Cache Optimization

Integrated Circuit Design Laboratory Project

- Built a 5-stage pipelined 16-bit CPU with AXI protocol and separate I/D cache to reduce memory latency
- Applied multi-stage multiplier to balance cycle time and timing closure

### Floating-Point CNN Accelerator for Similarity Matching

Integrated Circuit Design Laboratory Project

- Designed CNN accelerator with convolution, pooling, FC, activation
- Integrated IEEE-754 datapath using DesignWare FP IP
- Tuned for low latency and area efficiency